

Docket No.: 55551 CIP (71360)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANT: Kanayama, et al.

EXAMINER: D. J. Buttner

SERIAL NO.: 09/768,931

GROUP: 1712

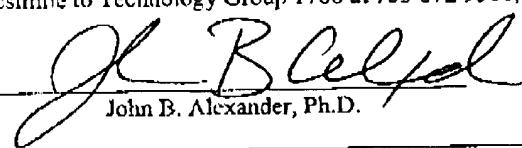
FILED: January 24, 2001

FOR: THERMOPLASTIC RESIN COMPOSITION MOLDED PRODUCT  
AND USE

Honorable Commissioner of Patents and Trademarks  
Box: AF  
Washington, DC 20231

**CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R. 1.8(A))**

I hereby certify that this Letter (along with any paper referred to as being attached or enclosed) is being transmitted to the United States Postal Service by facsimile to Technology Group 1700 at 703 872 9311, on April 9, 2003.

  
John B. Alexander, Ph.D.

Dear Sir:

**AMENDMENT AFTER FINAL PURSUANT TO 37 CFR § 1.116**

Applicants are in receipt of the Office Action dated December 23, 2002 and request reconsideration of the above-identified application in view of the following amendments and remarks.